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(54) Title: ADHESIVE COMPOSITION COMPRISING POLYHYDROXYETHER AND ORGANIC PARTICLES, AND METHOD FOR CONNECTING CIRCUIT BOARD USING THE SAME

(57) Abstract: To provide an adhesive composition which can exhibit high adhesion to a circuit board and also has ability capable of releasing the connection to the circuit board connected and reconnecting the circuit board (repairing properties). An adhesive composition comprising: (i) one or more aromatic-group-containing polyhydroxy ether resins, (ii) a compound having an alkoxysilyl group and an imidazole group in the molecule, and (iii) organic particles, wherein the content of the organic particles is 50% by weight or more based on the weight of the adhesive composition.

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